

Notice of References Cited	Application/Control No. 09/841,912	Applicant(s)/Patent Under Reexamination SMITH ET AL.	
	Examiner Russell Frejd	Art Unit 2128	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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	B	US-			
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	D	US-			
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	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

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NON-PATENT DOCUMENTS

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	U	SMITH et al., L.D. Power Distribution System Design Methodology and Capacitor Selection for Modern CMOS Technology, IEEE Transactions on Advanced Packaging, Vol. 22, No. 3, August 1999, pages 284-291.
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	W	MANDHANA, O.P. Design Oriented Analysis of Package Power Distribution System Considering Target Impedance for High Performance Microprocessors, Electrical Performance of Electronic Packaging, IEEE, October 2001, pages 273-276.
	X	SMITH et al., L.D. A Transmission-Line Model for Ceramic Capacitors for CAD Tools Based on Measured Parameters, Electronic Components and Technology Conference, IEEE, May 2002, pages 331-336.

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.